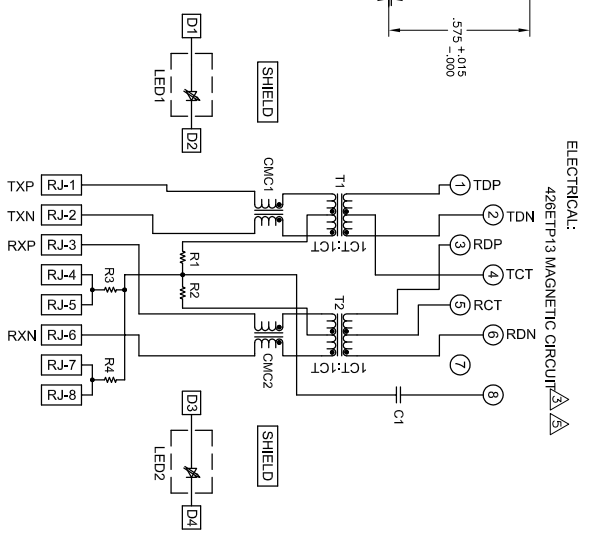
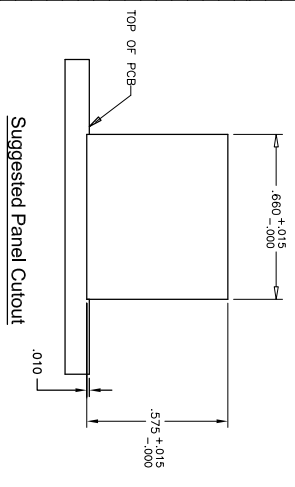
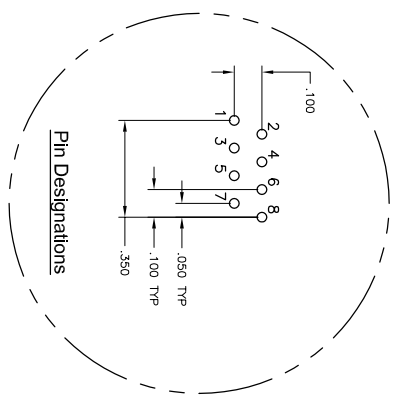
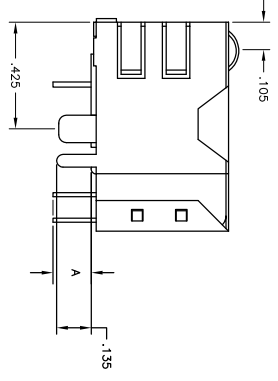
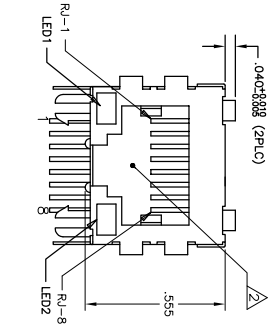
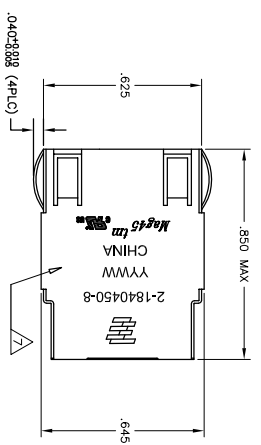
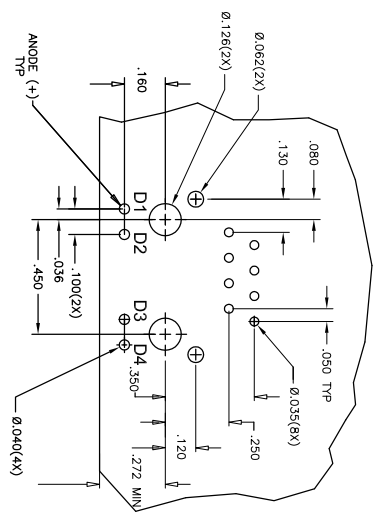


MECHANICAL:



C1=1000 pF 2KV DECOUPLING CAPACITOR
 R1-R4 = 75 Ohms, 1/16 W RESISTORS

Suggested PCB Layout (Component Side)



MATERIALS:

- HOUSING - THERMOPLASTIC PET POLYESTER ELASTICITY RATING UL 94V-0 SHIELD - .010" THICK, C26800 BRASS PREPLATED WITH 80μINCH MIN SEM-BRIGHT NICKEL. SOLDER TABS POST DIPPED WITH 100μINCH MIN SAC SOLDER. NOD JACK CONTACTS - 0.0157 X 0.018" PHOSPHOR BRONZE, 50μINCH MIN OVERFALL NICKEL UNDERPLATE WITH SELECT 50μINCH MIN HARD GOLD FINISH PLATE. SOLDER TABS WITH 100μINCH MIN MATTE TIN AND/OR SAC SOLDER DIP. LIGHT EMITTING DIODE(LED) - DIFFUSED EPOXY LENS, .020" X .020" CARBON STEEL WIREBOND LEADS PRE-PLATED WITH 80μINCH SILVER OVER 40μINCH NICKEL UNDERPLATE OVER 40μINCH COPPER UNDERPLATE. POST-PLATED WITH 100μINCH MIN MATTE TIN AND/OR SAC SOLDER DIP OR PURE TIN SOLDER DIP PART F.

MAGNETICS

- APPLICATION: 10/100 BASE-T, EXTENDED TEMPERATURE
- IMPEDANCE: 100 OHMS
- TURNS RATIO (GHP-CABLE): TX = 1:1, RX = 1:1
- OPEN CIRCUIT INDUCTANCE (OCL): 350μH MIN @100KHZ, 0 VPKS, 8mA DC BIAS FROM -40°C TO +85°C, TX AND RX
- PERFORMANCE @ 25°C:
- INSERTION LOSS (IL): 1.1dB MAX FROM 0.5MHZ TO 100MHZ
- RETURN LOSS (RL): 18dB MIN FROM 0.5MHZ TO 30MHZ
- 18-20LOGf/30DB MIN FROM 30.1MHZ TO 60MHZ
- 12dB MIN FROM 60.1MHZ TO 80MHZ
- CROSSTALK ATTENUATION: 35dB MIN FROM 0.5MHZ TO 100MHZ
- 33-20LOGf/50DB MIN FROM 1.0.1MHZ TO 100MHZ
- COMMON MODE REJECTION RATIO (CMRR): 30dB MIN FROM 0.5MHZ TO 100MHZ
- ISOLATION VOLTAGE: COMPLEYS WITH IEEE802.3 2002, PARA 23.5.1.1, ITEM b.

OPERATING TEMPERATURE: FROM -40° - +85°C.

- INDICATED CONNECTIONS ARE FOR NIC CONFIGURATION. THE MAGNETICS ARE SYMMETRICAL, AND THEREFORE SUPPORT AUTO-MDI/MDIX.
- LED IS DRIVEN WITH CONSTANT CURRENT AT APPROX 20mA
- DOMINANT WAVELENGTH(D)
- GREEN 555nm TYP. at IF=20mA
- TYCO ELECTRONICS LOGO, PART NUMBER, DATE CODE, COUNTRY OF ORIGIN AND AGENCY APPROVAL MARKING IN APPROXIMATE LOCATION SHOWN.
- THESE PARTS ARE RECOMMENDED FOR WAVE SOLDERING PROCESS. PREHEAT TEMPERATURE IS 70° C TO 80° C, 700 SECONDS TO 180 SECONDS PEAK WAVE SOLDERING TEMPERATURE IS 260° C (MAX), 10 SECONDS MAX.

REV	DATE	DESCRIPTION	BY	CHKD
AA	00	REVISIONS		
B		REV. RES. ECO-06-00000		
C		REV. RES. ECO-06-00000		
D		REV. RES. ECO-06-00000		

THIS DRAWING IS A CONTROLLED DOCUMENT

REVISIONS

DATE

DESCRIPTION

BY

CHKD

1202.010 YELLOW GREEN 2-1840450-9

1453.010 GREEN GREEN 5-1840450-7

1202.010 GREEN YELLOW 2-1840450-8

DIM A

LEAD 1

LEAD 2

PART NUMBER

1X1 MAGNETIC, 10/100 ETHERNET SCHEMATIC, 426ETP13 MAGNETIC, SHIELDED, DECOUPLING CAPACITOR, WHT LENS

100799

1840450

CUSTOMER DRAWING